

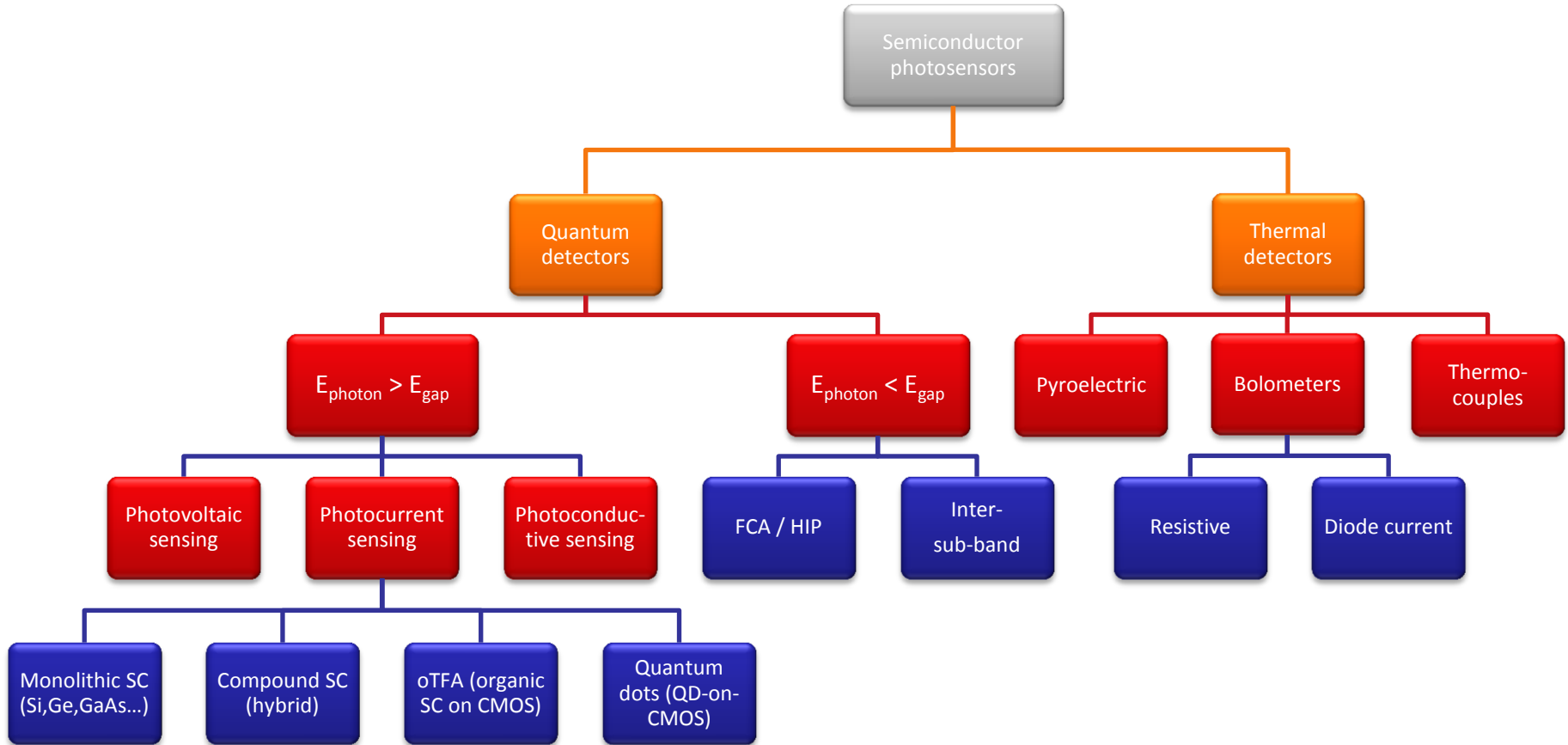
Solid-State Infrared Photosensing

Swiss Photonics Workshop, EMPA, 15 January 2015

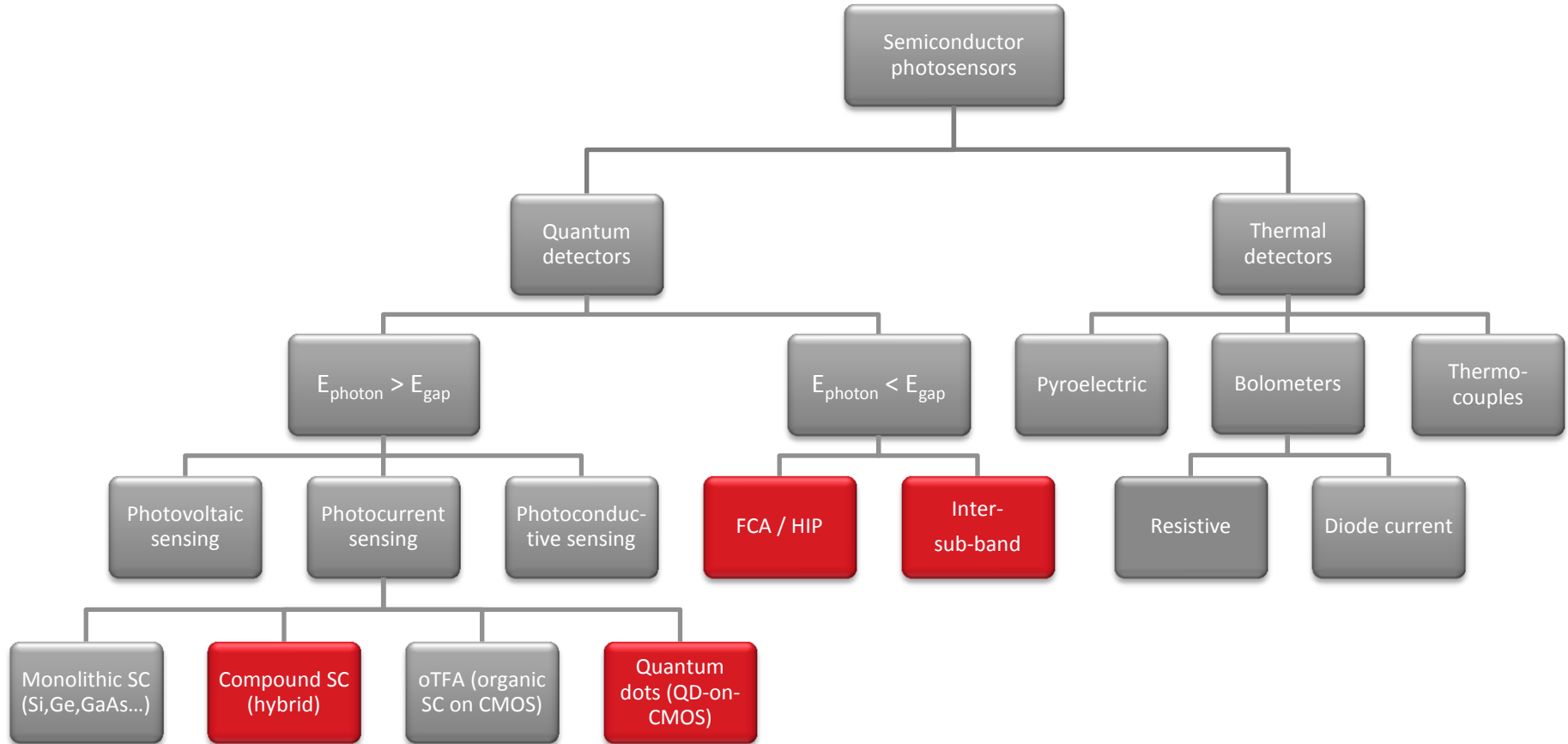
Peter Seitz

Head, Hamamatsu Photonics Innovation Center Europe, Solothurn, Switzerland
Adjunct professor of Optoelectronics, Institute of Microengineering, EPFL Lausanne
Deputy managing director, Innovation and Entrepreneurship Lab, ETH Zurich

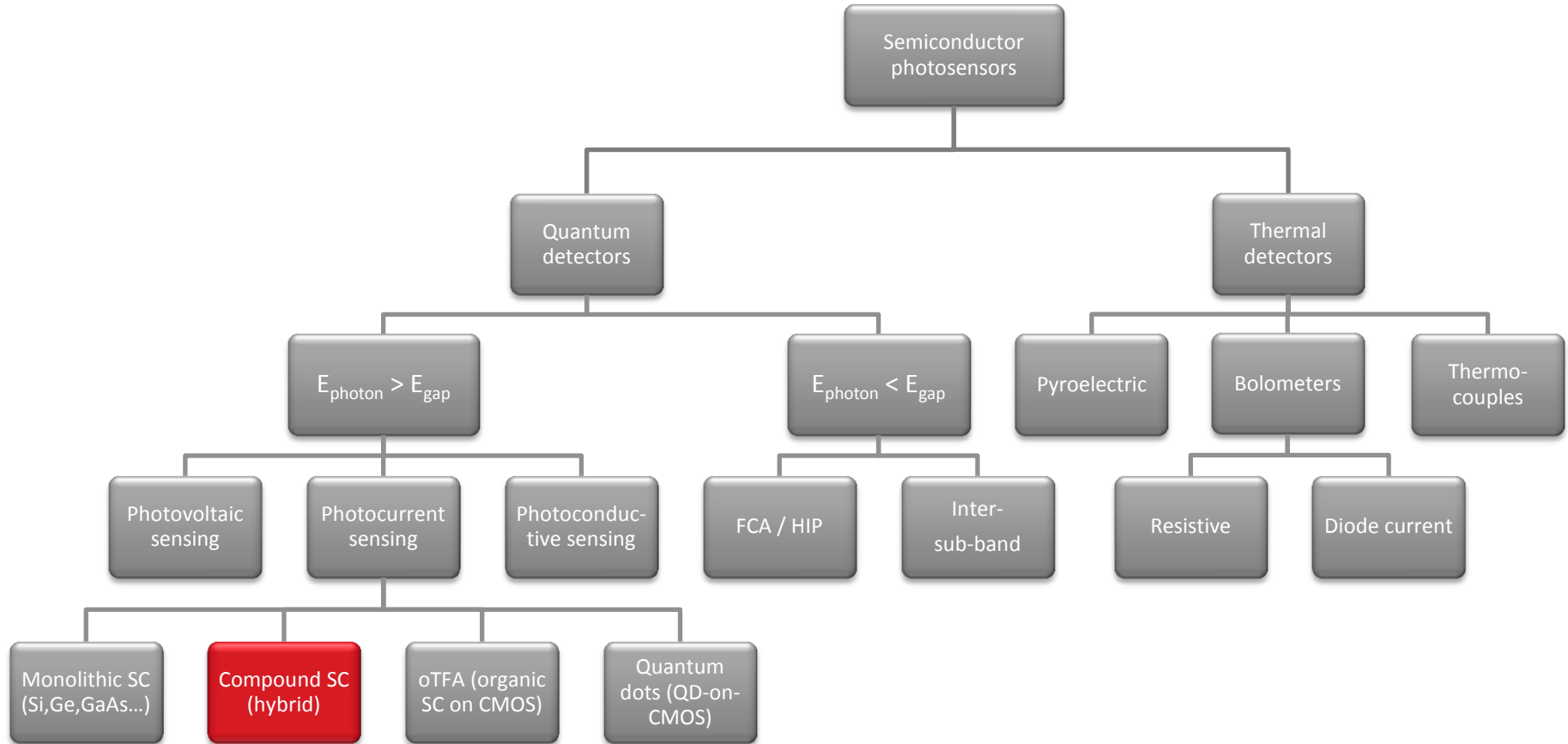
Taxonomy of Solid-State Photosensing Principles



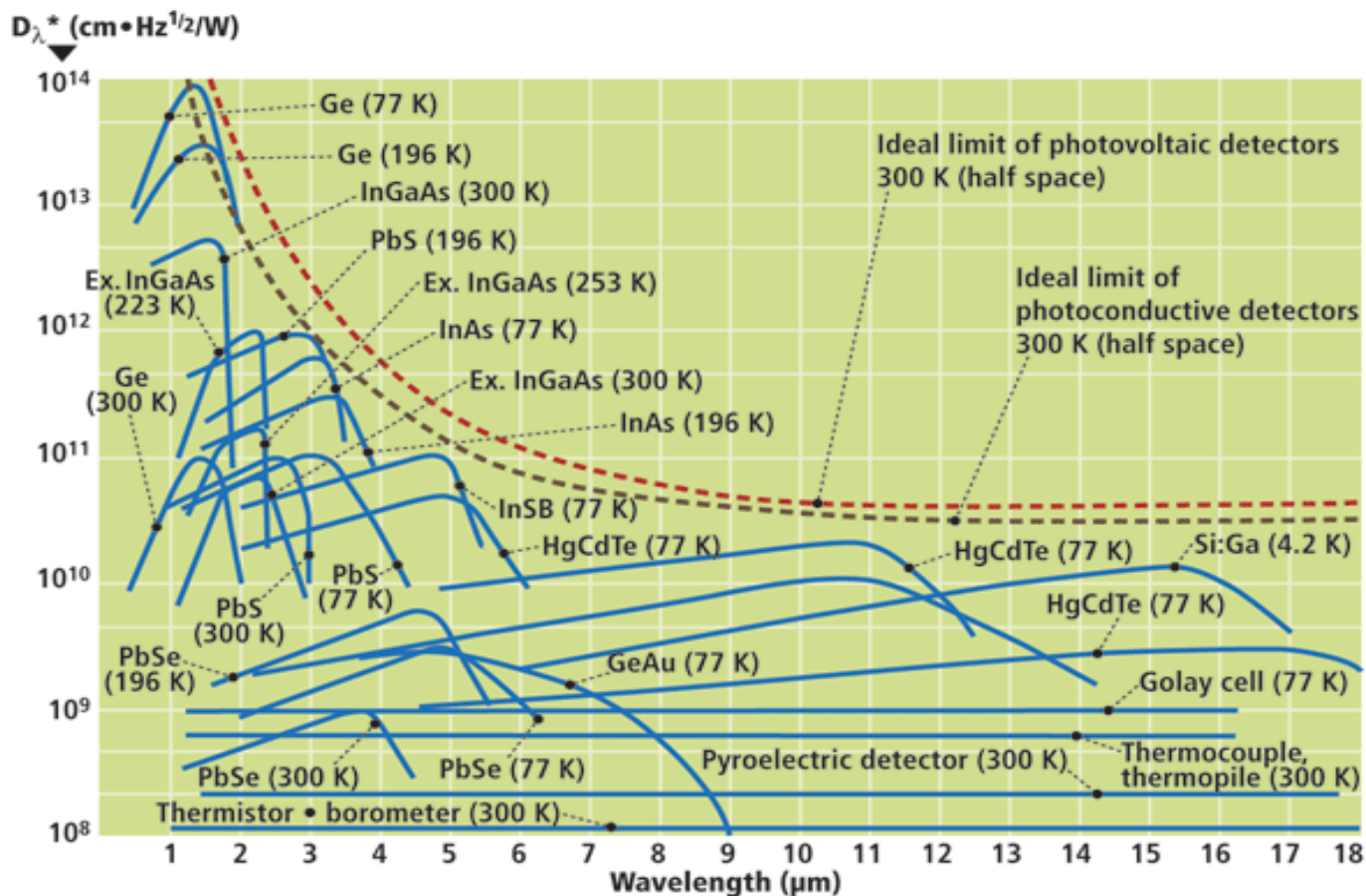
Contents of the Presentation



Compound Semiconductor Photosensors (on CMOS)



Detectivity of Different Types of Infrared Photosensor Materials



Andrew Wilson, "The Infrared Choice", Vision Systems Design, Vol. 16, 1 April 2011

InAsSb: Longest Wavelength III-V Semiconductor

In summary, this preliminary work has demonstrated room temperature InAsSb photodetectors operating up to $\approx 14 \mu\text{m}$ with performance close to the theoretical limits determined by fundamental limitations. The present InAsSb devices may be already useful for some applications (CO₂ laser monitors, laser warning receivers and others). The monolithic optical immersion should increase the performance to the level comparable to the state-of-art microbolometers, but with much faster speed of response. Further optimization of devices and the use of simple Peltier coolers should bring even improved performance, so that this technology may become a serious challenger to both MCT and microbolometer technologies.

M. Razeghi, "Longwavelength InAsSb Infrared Photodetectors", ARPA Report, April 1995

Mid-Infrared Quantum Detection: InAsSb

NEW

HAMAMATSU
PHOTON IS OUR BUSINESS

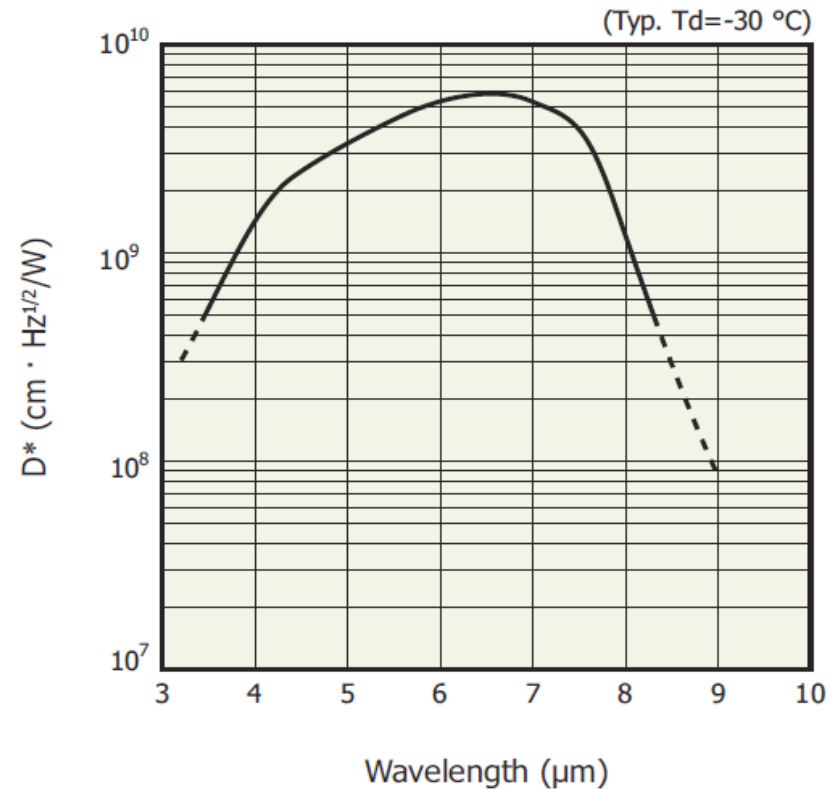
InAsSb photovoltaic detector



**High-speed resp
Thermoelectrica
required**

The P12691-201 is an infrared detector that provides high sensal growth technology and back-illuminated structure and by junction that ensures high-speed response and high reliability. and H₂S. The P12691-201 is easy to use as it uses a compact p

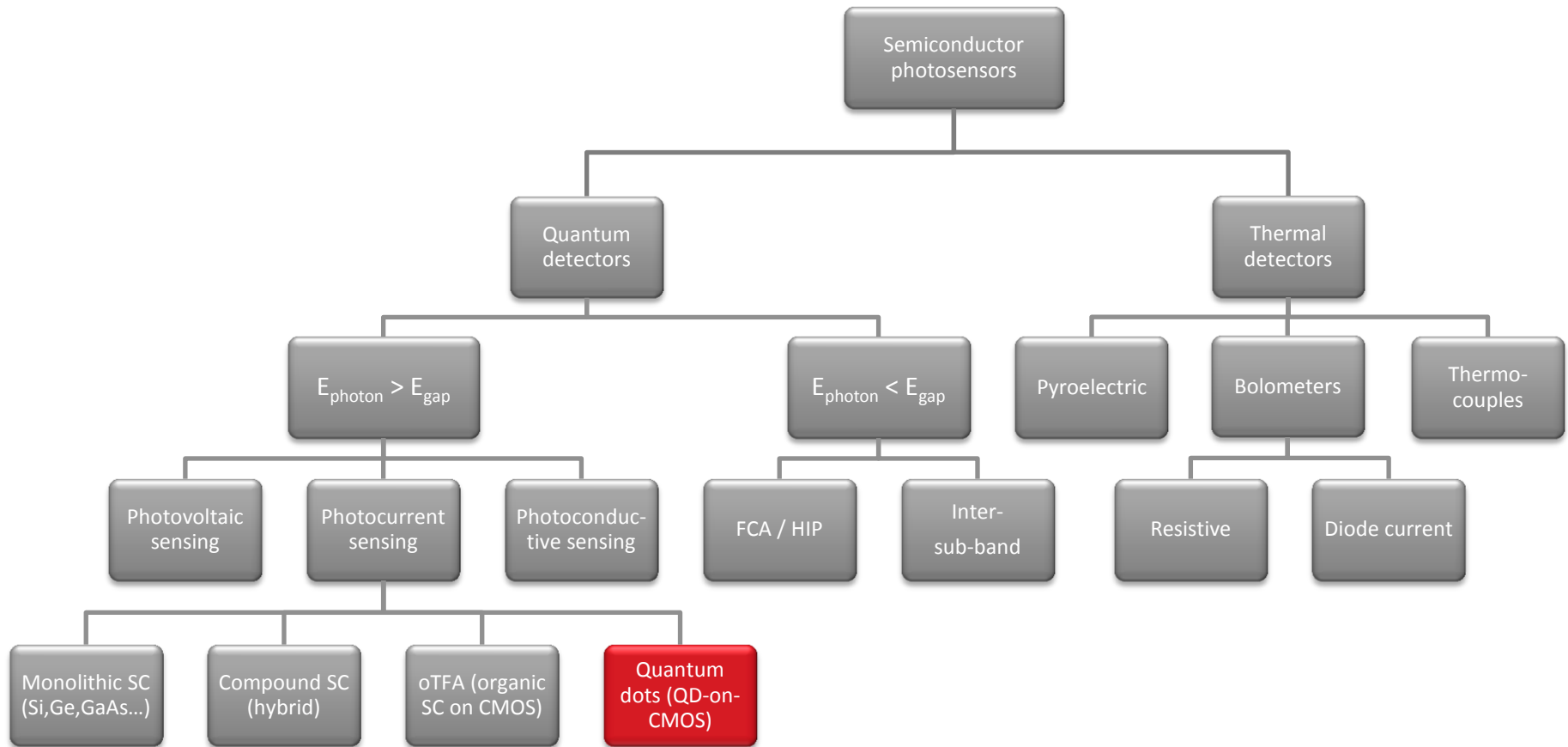
▣ Spectral response (D*)



▣ Features

- High-speed response
- High sensitivity
- High reliability
- Compact, thermoelectrically cooled TO-8 package
- RoHS compliant
- Can be assembled in a module with QCL

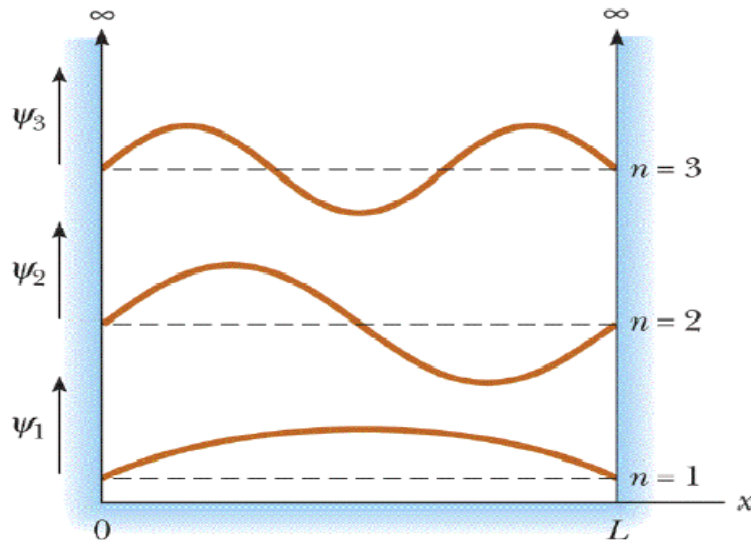
Quantum Dot Photosensing



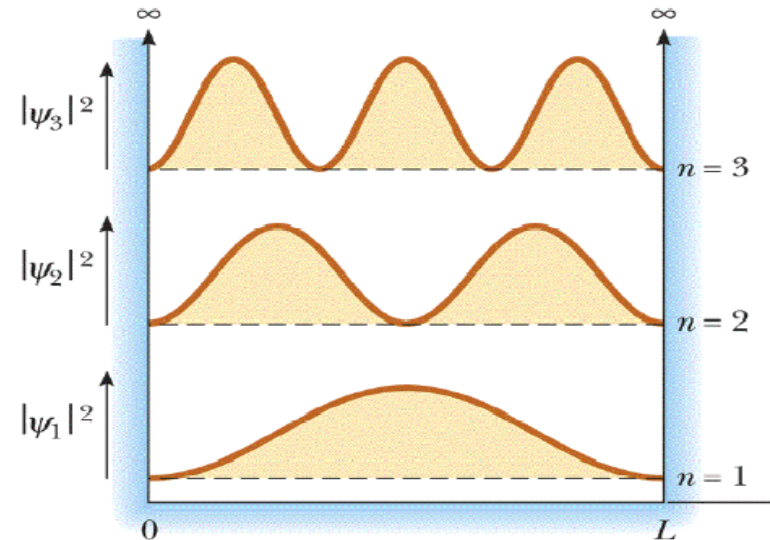
Reminder: Quantum Confinement Photodetection (Electron in a Box)

Potential energy: $U = 0$ in the box ($0..L$), and $U = \infty$ outside the box

$$\Psi_n(x) = \sqrt{\frac{2}{L}} \sin \frac{n\pi}{L} x \quad n = 1, 2, 3, \dots \quad E_n = \frac{h^2}{8mL^2} n^2$$

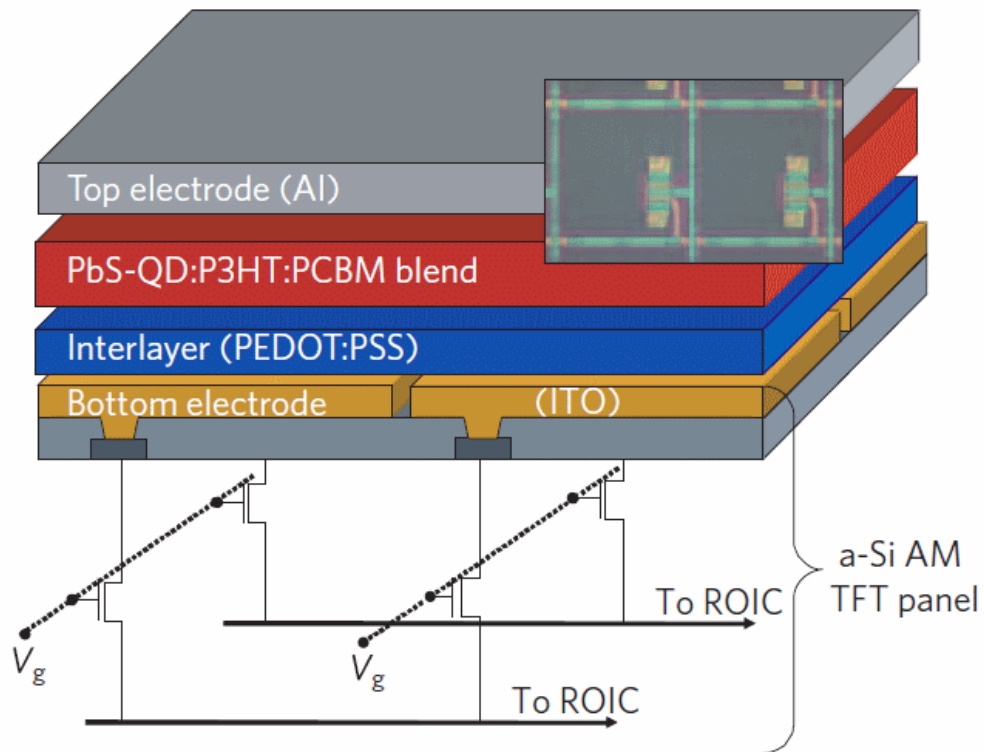


(a)



(b)

NIR/MIR Cutoff-on-Demand: Quantum-Dots on CMOS Image Sensors



T. Rauch et al., "Near-infrared imaging with quantum-dot-sensitized organic photodiodes", Nature Photonics, Vol. 3, 17 May 2009

MIR Wavelengths Accessible to Quantum-Dot Photosensing

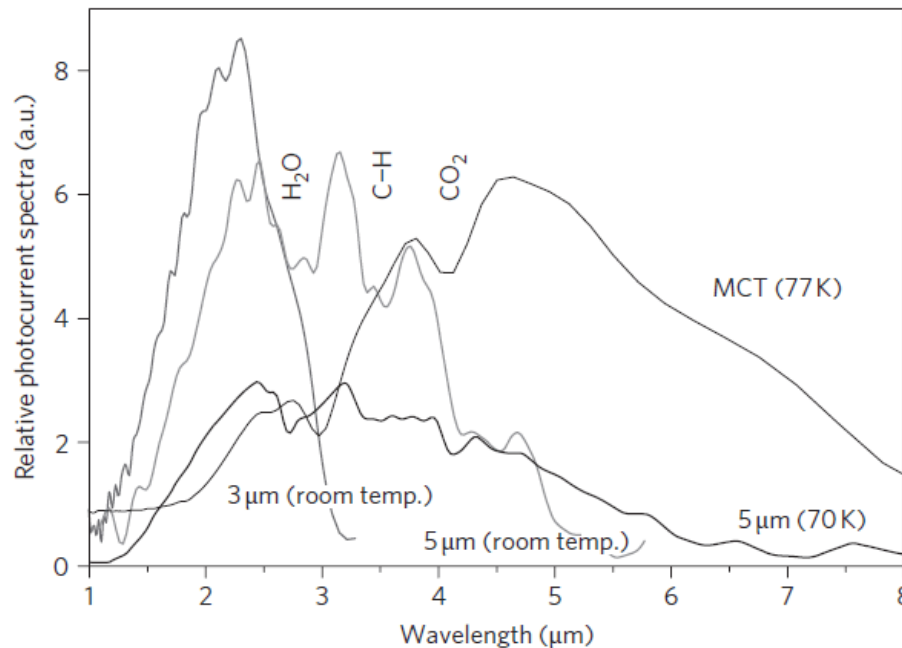
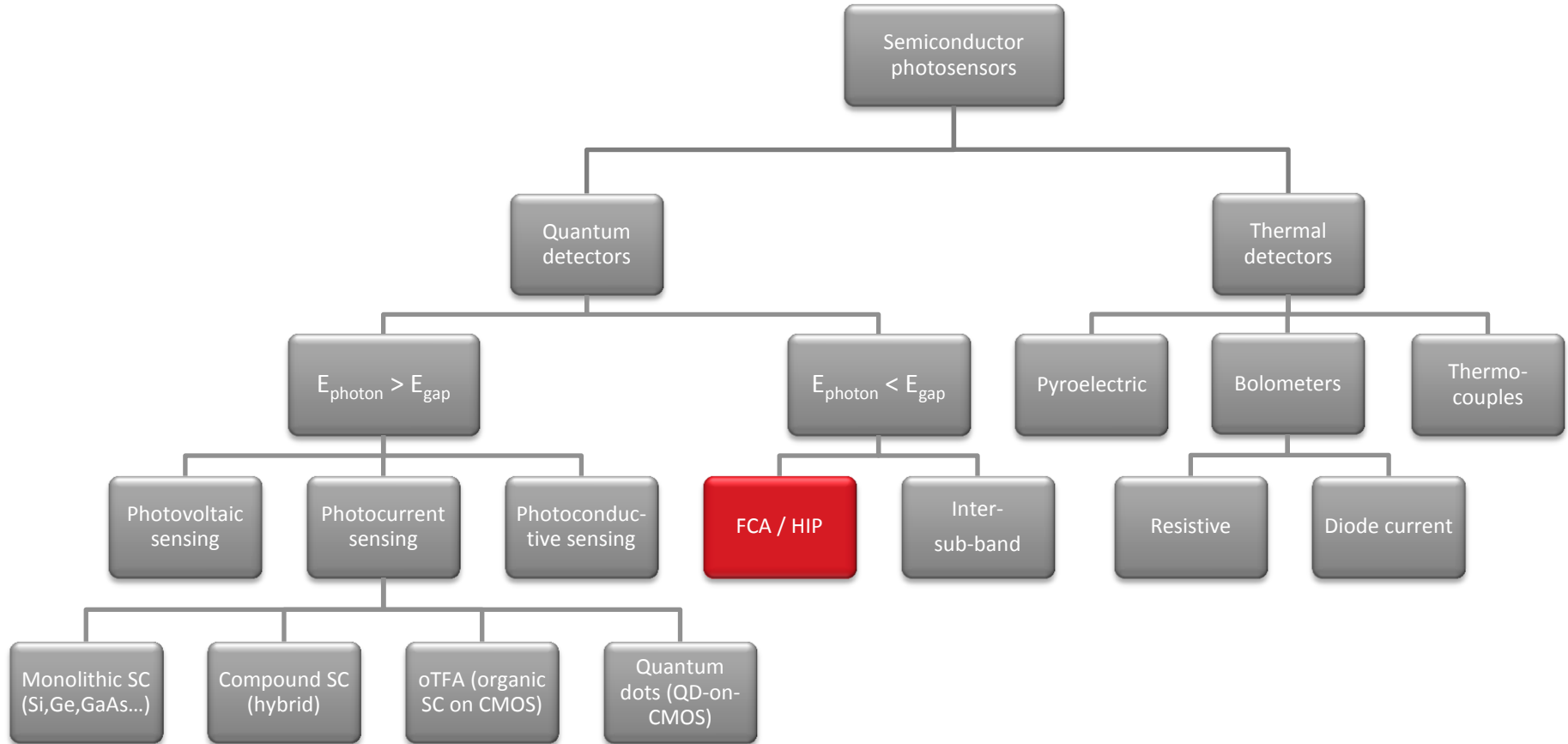


Figure 3 | Fourier transforms of interferograms measured for the two devices under identical conditions with 0.3 V bias. The 5 μm sample is shown at room temperature and at 70 K, and the 3 μm device at room temperature.

S. Keuleyan et al., "Mid-infrared HgTe colloidal quantum-dot photodetectors", Nature Photonics, Vol. 5, 17 Aug. 2011

Free Carrier Absorption – Homojunction Internal Photoemission



Silicon-Based (CMOS-Compatible) MIR/FIR Photosensing?

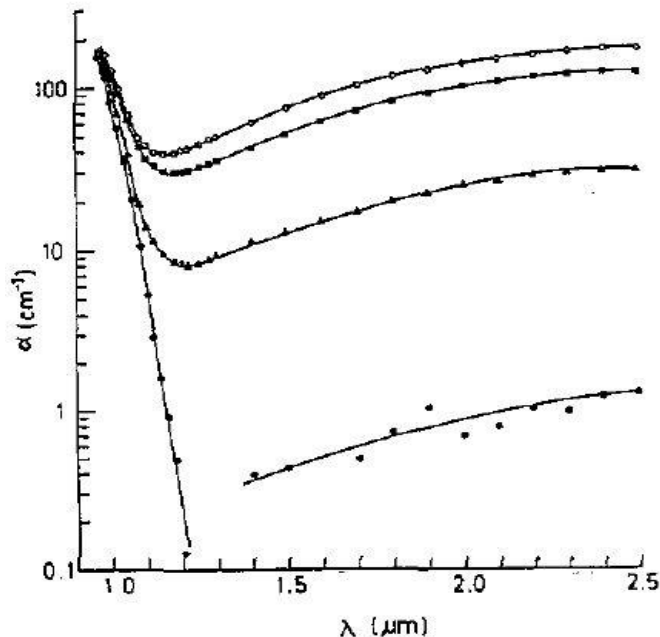


Figure 1. The absorption curves for n-Si samples at 294 K. (●) $6.5 \times 10^{16} \text{ cm}^{-3}$; (▲) $1.6 \times 10^{17} \text{ cm}^{-3}$; (■) $6.4 \times 10^{18} \text{ cm}^{-3}$; (○) $9.2 \times 10^{18} \text{ cm}^{-3}$.

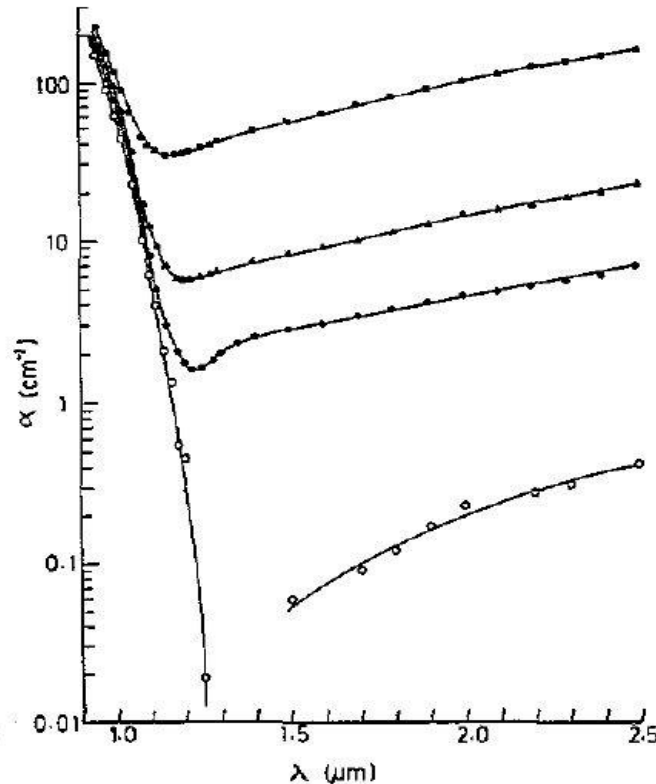


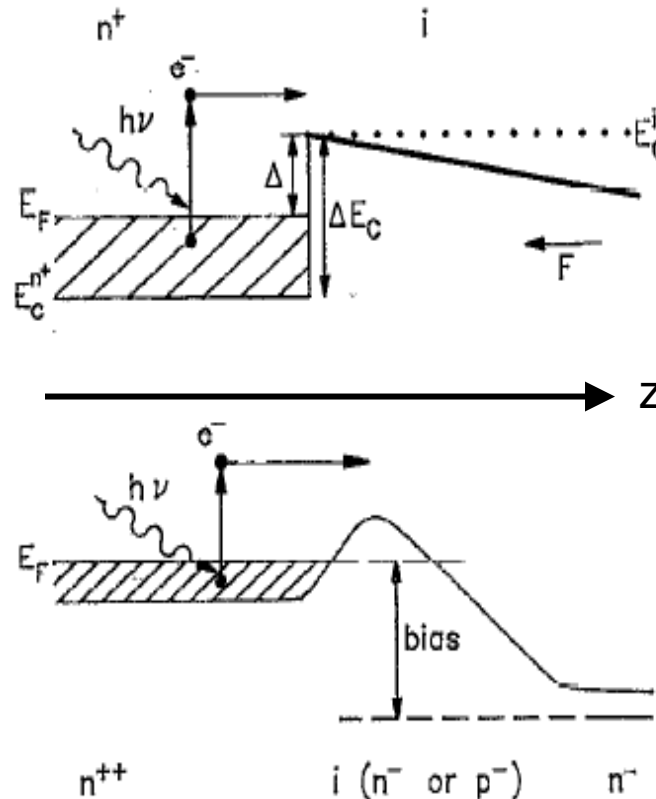
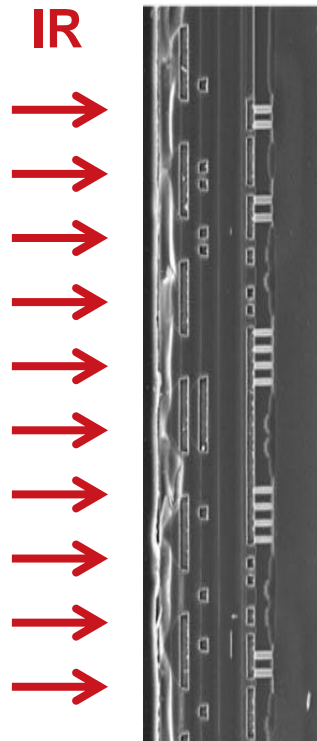
Figure 2. The absorption curves for p-Si samples at 294 K. (○) $1.5 \times 10^{16} \text{ cm}^{-3}$; (●) $3.3 \times 10^{17} \text{ cm}^{-3}$; (▲) $1.2 \times 10^{18} \text{ cm}^{-3}$; (■) $7.3 \times 10^{18} \text{ cm}^{-3}$.

IR absorption in doped Si is increasing with the square of the wavelength

Relationship holds up to wavelengths of several 100 μm (FIR / THz)

S.E. Aw et al., "Optical absorption measurements of bandgap shrinkage in moderately and heavily doped silicon", J. Phys. Cond. Matter Vol. 3, 1991

Ultra-Wide-Band NIR/MIR/FIR/THz Silicon Photodetection: FCA/HIP



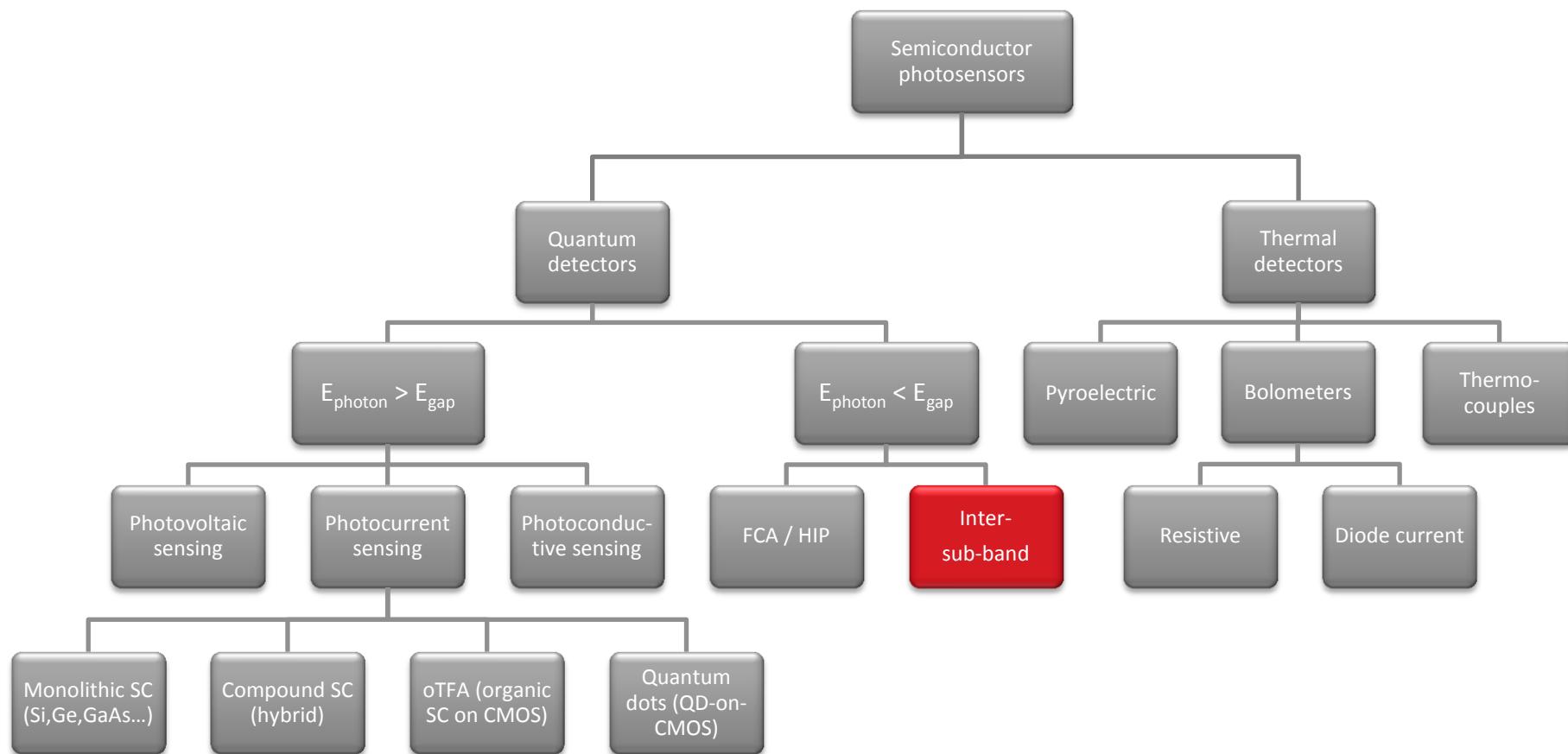
Potential barriers close to the surface, next to highly doped silicon, act as filters for charge carriers excited by the incident IR photons:

Only higher-energy electrons/holes can pass over the barrier, for collection and detection by adjacent electronic circuits

A.G.U. Perera et al., "Homojunction internal photoemission far-infrared detectors: Photoresponse performance analysis", *J. Appl. Phys.* 77 (2), 1995

HIP = Homojunction internal photoemission

Intersubband Infrared Photodetection



Infrared Photodetection With A Silicon Gate (MOS) Structure



US006420707B1

(12) **United States Patent**
Anthony et al.

(10) **Patent No.:** **US 6,420,707 B1**
(45) **Date of Patent:** **Jul. 16, 2002**

(54) **INFRA-RED DETECTOR**

OTHER PUBLICATIONS

(75) Inventors: **Carl J. Anthony; Kevin M. Brunson; Charles T. Elliott; Neil T. Gordon; Timothy J. Phillips; Michael J. Uren,** all of Malvern (GB)

T. Ando, "Inter-Subband Optical Absorption in Space-Charge Layers on Semiconductor Surfaces" *Z. Physik B*, 26, pp. 263-272 (1977).
Ryzhii V; "An Infrared Lateral Hot-Electron Phototransistor" *Semiconductor Science and Technology*, vol. 9, No. 7.

(73) Assignee: **Qinetiq Limited**, London (GB)

(*) Notice: Subject to any disclaimer, the term of patent is extended or adjusted under U.S.C. 154(b) by 0 days.

(21) Appl. No.: **09/297,176**

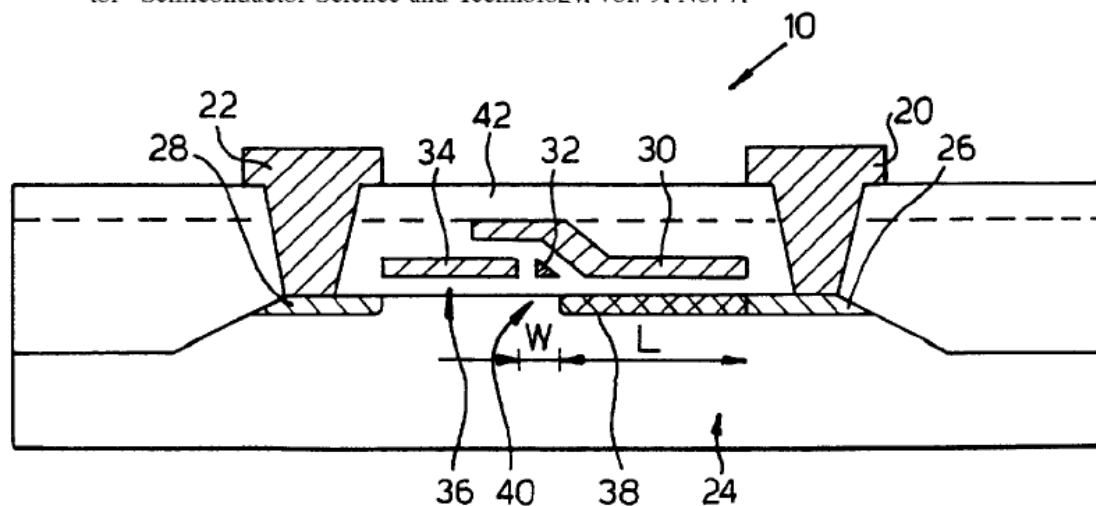
(22) PCT Filed: **Nov. 6, 1997**

(86) PCT No.: **PCT/GB97/03053**

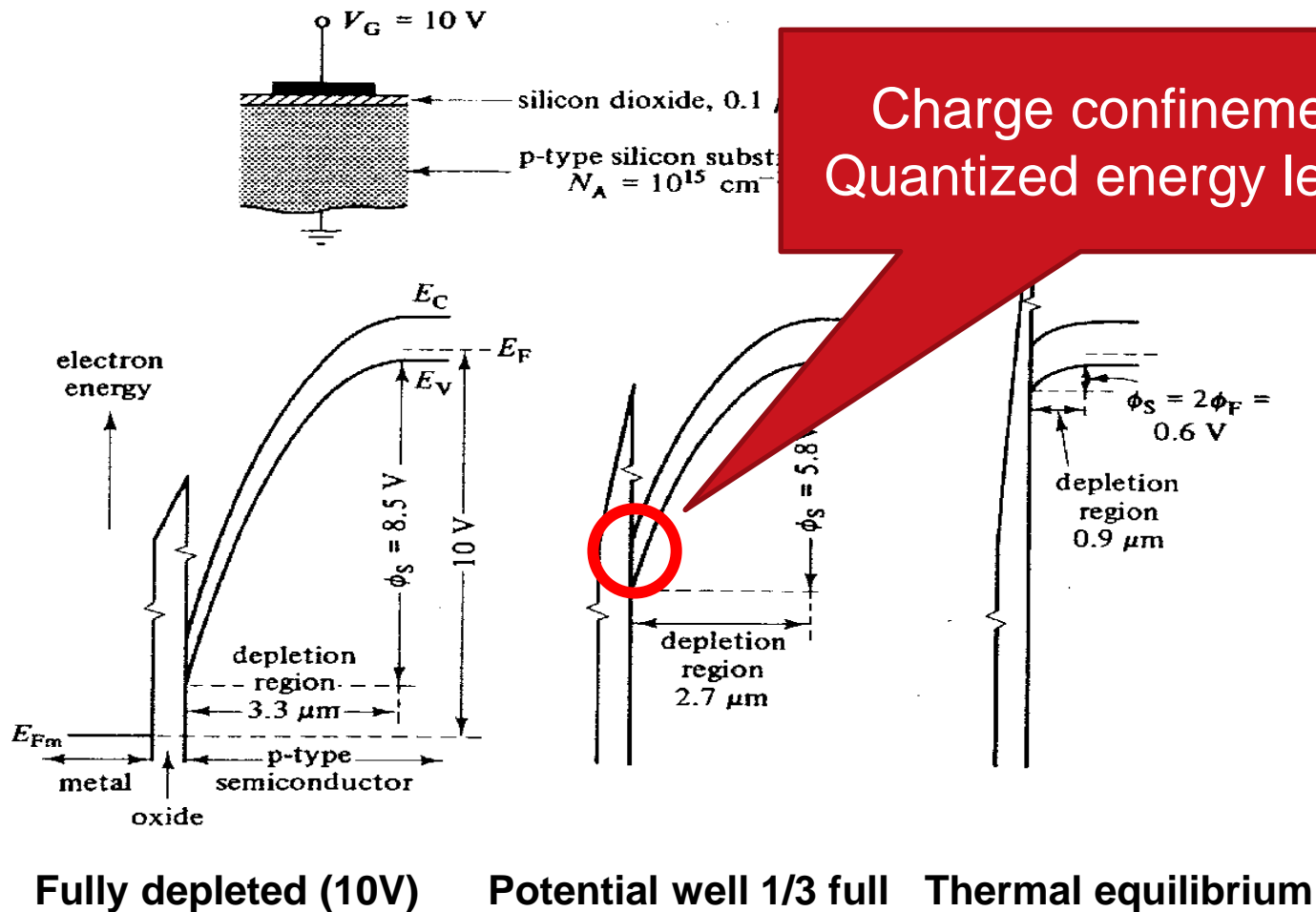
§ 371 (c)(1),
(2), (4) Date: **Jul. 21, 1999**

(87) PCT Pub. No.: **WO98/21757**

PCT Pub. Date: **May 22, 1998**

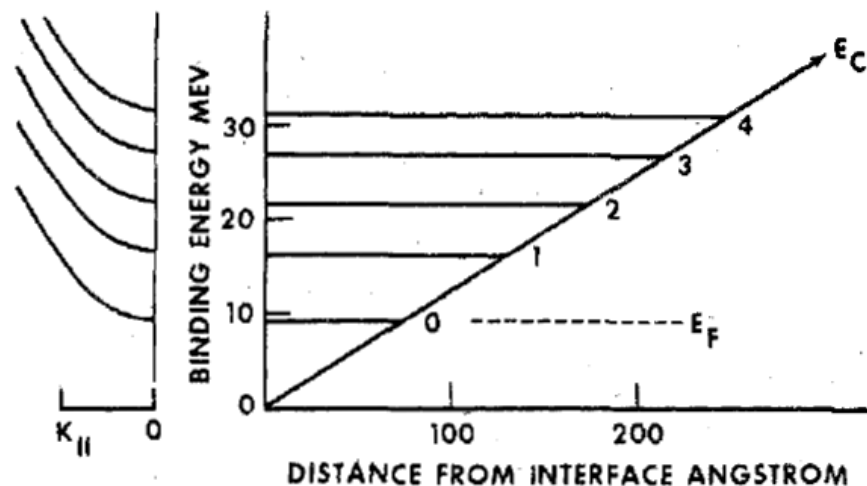


Potential Distribution In A (Silicon) MOS Structure



Charge confinement -
Quantized energy levels !

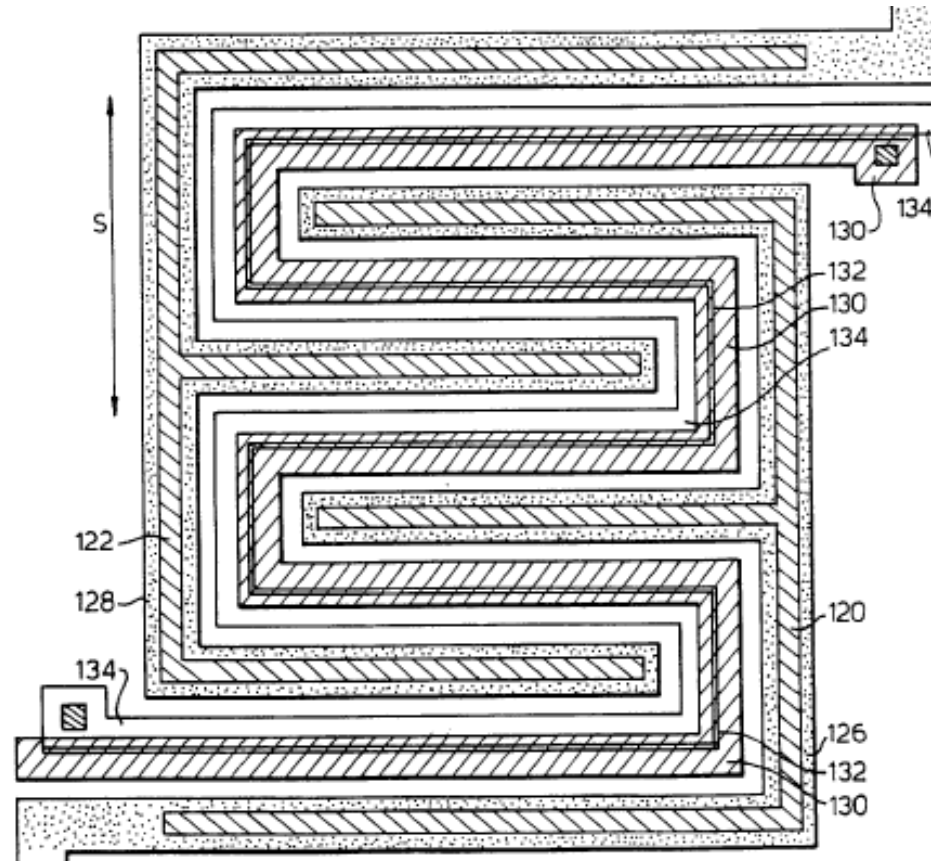
Silicon-Based Inter-Subband Voltage-Tuneable Infrared Detectors



Energies of the lowest four electric subbands for a 001 silicon surface whose p-type substrate contains 4.5×10^{14} acceptors/cm³ uniformly distributed. The ellipsoidal nature of the electron conduction bands implies two possible m_z values leading to two discrete electric band ladders. Since transitions between states derived from different mass are forbidden in the dipole approximation, the diagram does not show the light mass ladder.

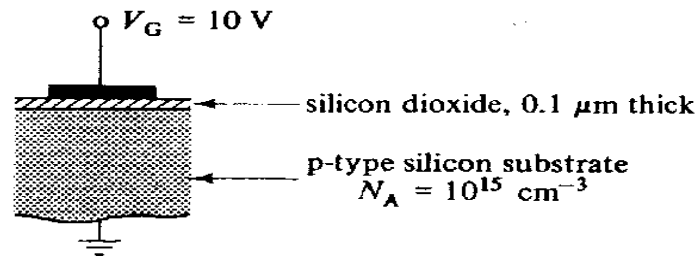
R. G. Wheeler and H. S. Goldberg, "A Novel Voltage Tuneable Infrared Spectrometer-Detector", IEEE Trans ED-22 (1975)

Silicon-Based Inter-Subband Voltage-Tuneable Infrared Detectors



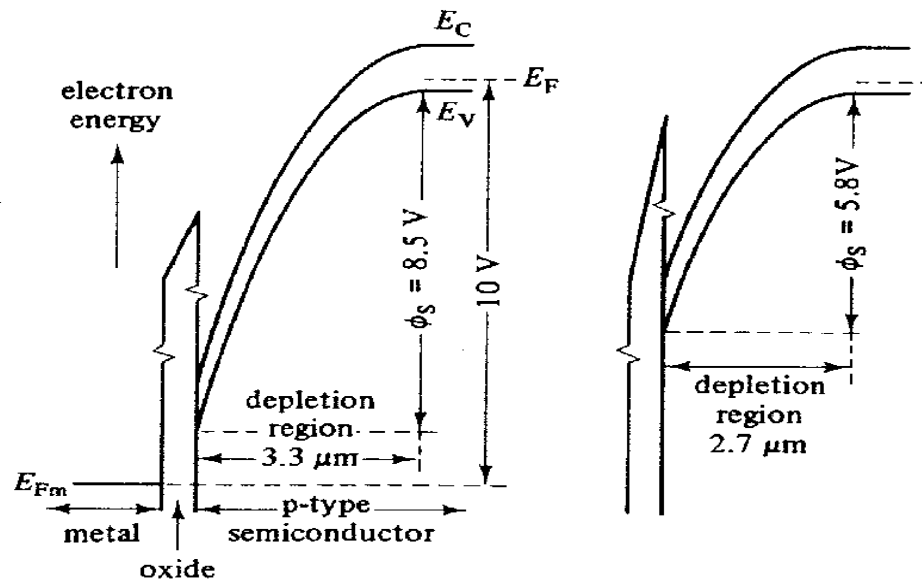
C.J. Anthony et al. (Qinetiq), "Infra-Red Detector", US Patent No. 6,420,707 B1, 2002

Inter-Subband Voltage-Tuneable Silicon Infrared Detectors



Potential slope dV/dz
(max. electric field) at
silicon/oxide interface:

$$E_{max} = \sqrt{\frac{2q}{\epsilon_0 \epsilon_{Si}} N_S V_G}$$



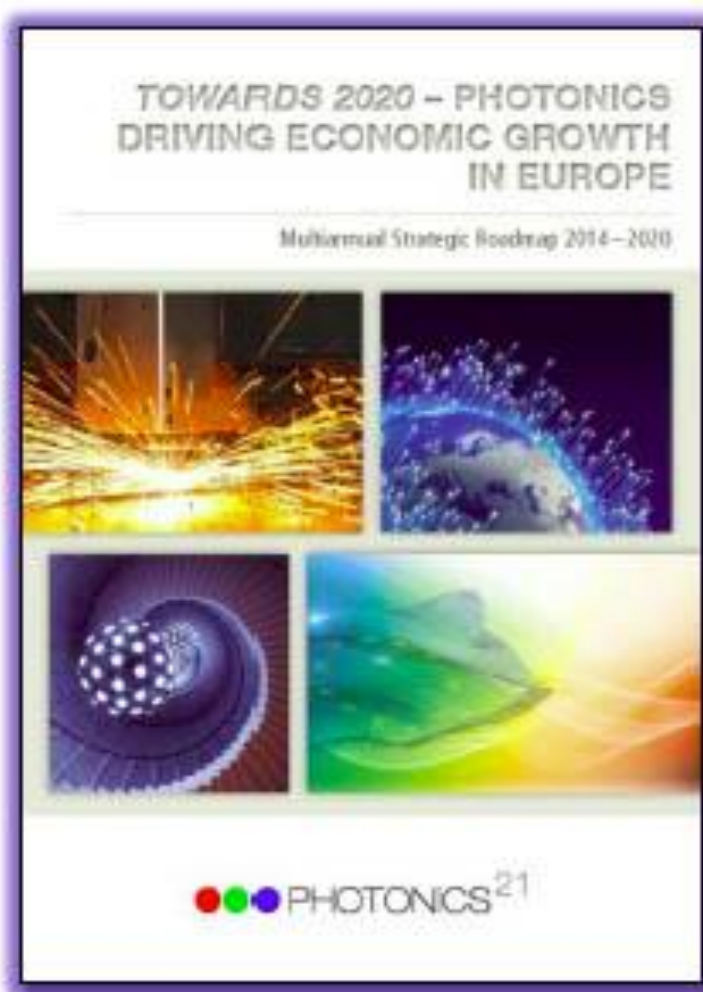
Fully depleted (10V)

Potential well 1/3 full

V_G : Gate voltage
 N_S : Substrate doping

**Device design and
Si technology !**

Affordable Solid-State Infrared Photodetection and Image Sensing



2. Photonics Research and Innovation Challenges

61



Photonic technologies can help retailers and customers to judge the ripeness of fruit and vegetables, and so reduce the percentage of discarded food. © Fraunhofer IPA

The overall goal is to conquer the EIR [*Extended Infrared Spectral Range*] with a complete toolbox of low-cost active and passive photonic devices [*100x cheaper*] ...

and condensed phases. Finally, the far infrared and THz region (up to 1000 μm) offers complementary fingerprinting capabilities using specific spectral signatures, with the additional benefit of deep penetration in standard packaging materials such as paper, plastics or textiles.

Some of these critical measurements in the extended infrared (EIR) spectral domain (1-1000 μm) can be performed today, albeit with very expensive active and passive photonic components. For example, a moderate-power MIR laser costs €10,000, an uncooled FIR bolometer camera costs at least €50,000, a 128x128 NIR image sensor (InGaAs) costs €4000, a single photodiode (InAsSb) for the 1-5 μm band costs €1000, and even a single silicon microlens (for wavelengths above 1.1 μm) costs €50. Clearly it is not currently possible to realise

conductor materials, offering EIR properties.

- CMOS-based charge detectors with low-noise/low-power/high-performance that can be integrated in classes of semiconductor materials
- novel measurement techniques exploiting the beneficial properties of quantum-well EIR detectors for individual applications
- affordable non-toxic materials (in particular thermo-electric materials) for EIR photo-sensing and light emission systems
- a wide range of low-cost passive optical components, to enable the integration of complete EIR systems.

The overall goal is to conquer the EIR spectral range with a complete toolbox of low-cost active and

Thank you very much!

www.hamamatsu.eu